

FS5AS-06

High-Speed Switching Use Nch Power MOS FET

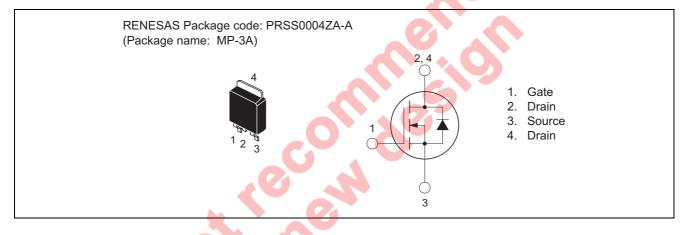
REJ03G1404-0200 (Previous: MEJ02G0087-0101) Rev.2.00 Aug 07, 2006

2500

Features

- Drive voltage : 10 V
- V_{DSS} : 60 V
- $r_{DS(ON)(max)}$: 0.16 Ω
- I_D: 5 A
- Integrated Fast Recovery Diode (TYP.): 45 ns

Outline



Applications

Motor control, Lamp control, Solenoid control, DC-DC converters, etc.

Maximum Ratings

				$(1c = 25^{\circ}C)$
Parameter	Symbol	Ratings	Unit	Conditions
Drain-source voltage	V _{DSS}	60	V	$V_{GS} = 0 V$
Gate-source voltage	V _{GSS}	±20	V	$V_{DS} = 0 V$
Drain current	I _D	5	А	
Drain current (Pulsed)	I _{DM}	20	А	
Avalanche drain current (Pulsed)	I _{DA}	5	А	L = 100 μH
Source current	ls	5	А	
Source current (Pulsed)	I _{SM}	20	А	
Maximum power dissipation	PD	20	W	
Channel temperature	Tch	- 55 to +150	°C	
Storage temperature	Tstg	- 55 to +150	°C	
Mass	_	0.32	g	Typical value

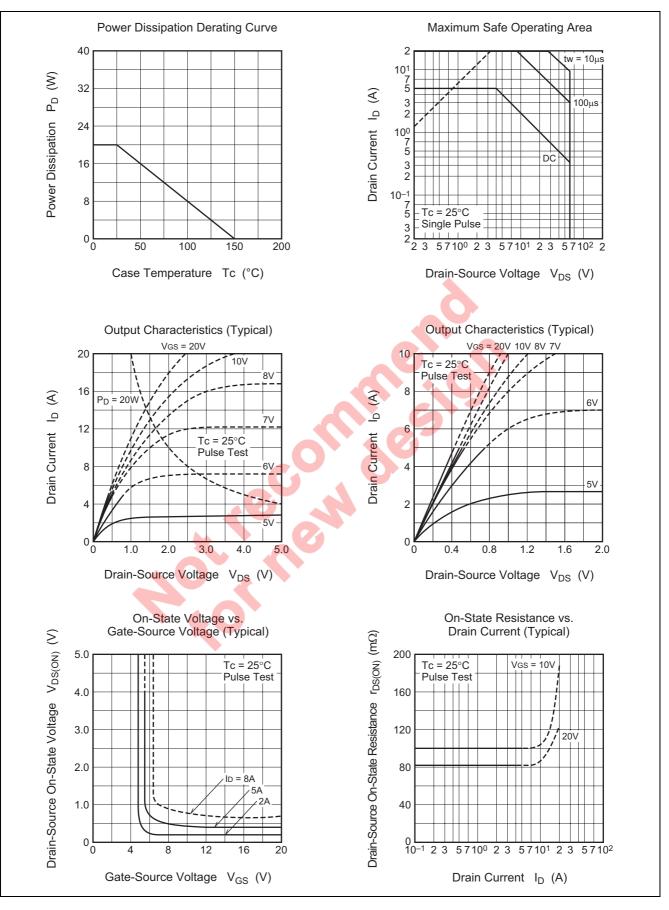


Electrical Characteristics

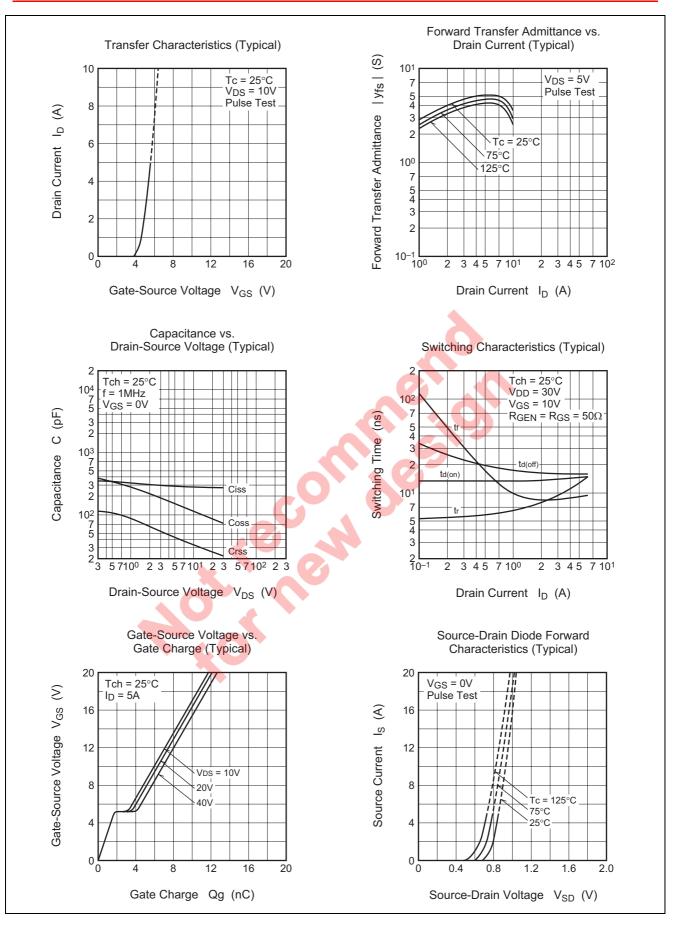
	-					$(Tch = 25^{\circ}C)$
Parameter	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain-source breakdown voltage	V _{(BR)DSS}	60	—	—	V	$I_{D} = 1 \text{ mA}, V_{GS} = 0 \text{ V}$
Gate-source leakage current	I _{GSS}	_	—	±0.1	μA	V_{GS} = ±20 V, V_{DS} = 0 V
Drain-source leakage current	I _{DSS}	_	—	0.1	mA	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$
Gate-source threshold voltage	V _{GS(th)}	2.0	3.0	4.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Drain-source on-state resistance	r _{DS(ON)}	_	0.12	0.16	Ω	$I_D = 2 \text{ A}, V_{GS} = 10 \text{ V}$
Drain-source on-state voltage	V _{DS(ON)}	_	0.24	0.32	V	$I_D = 2 \text{ A}, V_{GS} = 10 \text{ V}$
Forward transfer admittance	y _{fs}	_	4.0	—	S	$I_D = 2 \text{ A}, V_{DS} = 5 \text{ V}$
Input capacitance	Ciss	_	280	—	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V},$
Output capacitance	Coss	_	120	—	pF	f = 1MHz
Reverse transfer capacitance	Crss		35	—	pF	
Turn-on delay time	t _{d(on)}	_	15	—	ns	$V_{DD} = 30 \text{ V}, \text{ I}_{D} = 2 \text{ A},$
Rise time	tr	_	8	—	ns	V _{GS} = 10 V,
Turn-off delay time	t _{d(off)}	_	18	—	ns	$R_{GEN} = R_{GS} = 50 \ \Omega$
Fall time	t _f	_	9		ns	
Source-drain voltage	V _{SD}		1.0	1.5	V	$I_{S} = 2 \text{ A}, V_{GS} = 0 \text{ V}$
Thermal resistance	R _{th(ch-c)}		_	6.25	°C/W	Channel to case
Reverse recovery time	t _{rr}		45		ns	I _S = 5 A, d _{is} /d _t = −100 A/μs



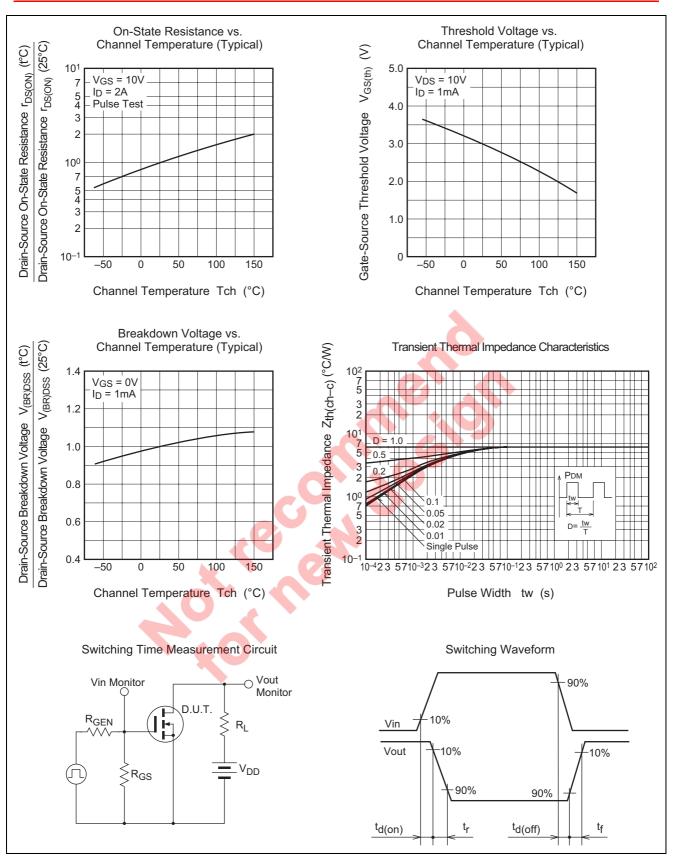
Performance Curves



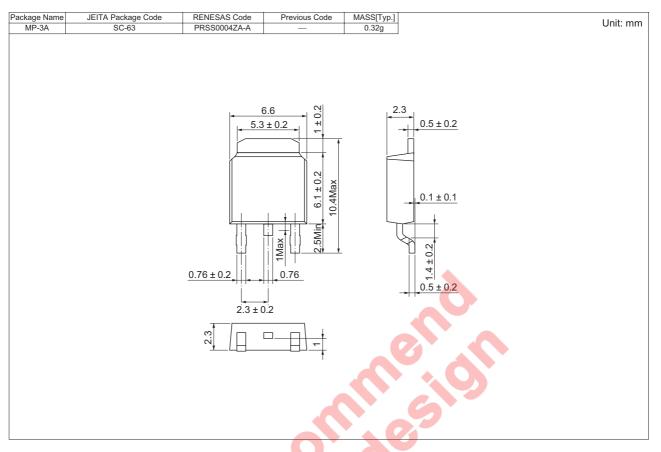








Package Dimensions



Order Code

Lead form	Standard packing	Quantity	Standard order code	Standard order code example
Surface-mounted type	Taping	3000	Type name – T +Direction (1 or 2) +3	FS5AS-06-T13
Surface-mounted type	Plastic Magazine (Tube)	75	Type name	FS5AS-06

Note : Please confirm the specification about the shipping in detail.

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